

SSC8039HN6

P-Channel Enhanced MOSFET

Features

VDS	VGS	RDSON Typ.	ID
201/	1201/	7mΩ@-10V	644
-30V	±20V	8.5mΩ@-4V5	-64A

Description

The SSC8039HN6 P-Channel enhancement MOSFET. Uses advanced trench technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. 100% UIS + DVDS Tested.

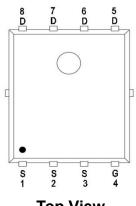
Applications

- DC/DC conversion
- Power management in portable
- Load/Power Switching for portable device

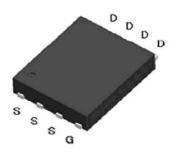
Ordering Information

Device	Package	Shipping		
SSC8039HN6	PDFN5X6-8L	5000/Reel		

Pin configuration



Top View



PDFN5X6-8L



Marking

(XXYY: Traceability Code)

Rev.1.0 www.sscsemi.com



Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

Symbol	Parameter		Ratings	Unit
V _{DSS}	Drain-to-Source Vol	Drain-to-Source Voltage		V
V _{GSS}	Gate-to-Source Volt	tage	±20	V
	Continuous Drain Current	T _C =25℃	-64	
I _D	Continuous Drain Current	T _C =100℃	-34	Α
	Continuous Dusin Comment 3	T _A =25℃	-18.5	
I _{DSM}	Continuous Drain Current ^a	T _A =70℃	-13	Α
I _{DM}	Pulsed Drain Curre	ent ^b	-120	Α
В	Dower Discipation 6	T _C =25℃	29	\\\\\
P _D	Power Dissipation ^c	T _C =100℃	11.6	W
В	Dower Discinction 8	T _A =25℃	2.4	10/
P _{DSM}	Power Dissipation ^a	T _A =70℃	1.5	W
I _{AS}	Avalanche Current ^b L=0.5mH	Single Pulse	-22.5	Α
Eas	Avalanche Energy ^b L=0.5mH	l Single Pulse	126	mJ
TJ	Operation junction temperature		-55~150	$^{\circ}$
T _{STG}	Storage temperature	range	-55~150	
R _{0JA}	Junction-to-Ambient Thermal	Resistance ^a	52	°C/W
Rejc	Junction-to-Case Thermal	4.3	C/VV	

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper,in a still air environment with T_A=25℃. The value in any given application depends on the user is specific board design. The current rating is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

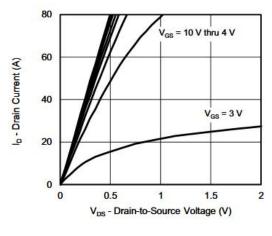


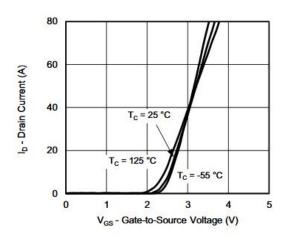
\triangleright Electronics Characteristics (T_A=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	VGS=0V, ID=-250uA	-30			V	
V _{GS(th)}	Gate Threshold Voltage	VDS=VGS, ID=-250uA	-1	-1.6	-2	V	
	Drain-Source	VGS=-10V, ID=-20A		7	8.5		
$R_{DS(on)}$	On-Resistance	VGS=-4.5V, ID=-12A		8.5	12	mΩ	
I _{DSS}	Zero Gate Voltage Drain Current	VDS=-24V, VGS=0V			-1	μA	
I _{GSS}	Gate-Source leak	VGS=±20V, VDS=0V			±100	nA	
G _{FS}	Transconductance	VDS=-10V, ID=-5A		38		S	
V _{SD}	Forward Voltage	VGS=0V, IS=-2A		-0.7	-1.3	V	
Ciss	Input Capacitance			4900			
Coss	Output Capacitance	VDS=-15V, VGS=0V,		440		pF	
Crss	Reverse Transfer Capacitance	f=1MHz		330			
$T_{D(ON)}$	Turn-on delay time	V00- 40V DI -450		44			
Tr	Rise time	VGS=-10V, RL=15 Ω VDS=-15V, RG=6 Ω ,		31		200	
$T_{D(OFF)}$	Turn-off delay time	VD315V, RG-012,		188		ns	
Tf	Fall time	ID2A		111			
Q_{G}	Total Gate Charge			66			
Q _{GS}	Gate to Source Charge	VGS=-10V, VDS=-15V ID=-20A		9		nC	
Q_GD	Gate to Drain Charge			15			



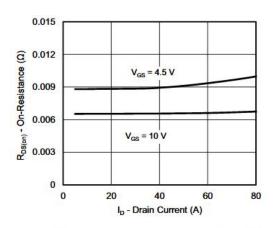
➤ Typical Characteristics (T_A=25°C unless otherwise noted)

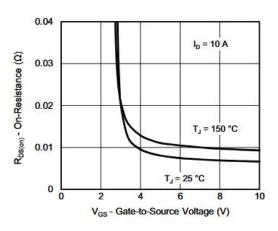




Output Characteristics

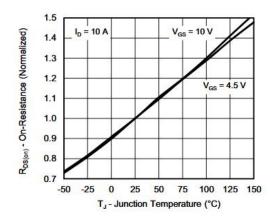
Transfer Characteristics

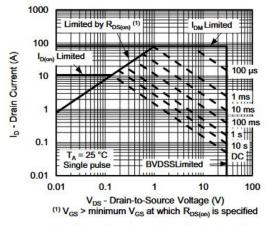




On-Resistance vs. Drain Current and Gate Voltage

On-Resistance vs. Gate-to-Source Voltage



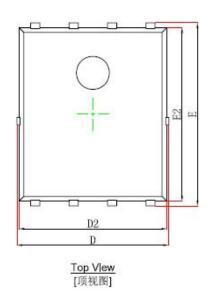


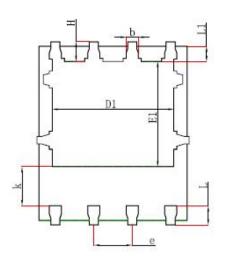
On-Resistance vs. Junction Temperature

Safe Operating Area, Junction-to-Ambient

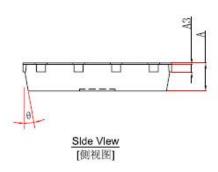


> Package Information





Bottom Vlew [背视图]



PDNF5X6-8L

Comple el	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
Α	0.900	1.000	0.035	0.039
A3	0.254REF		0.010REF	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
е	1.270TYP		0.050TYP	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
Н	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°



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